

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TPS7A1015PDESET"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS7A1015PDESET	NIPDAUAG	Level-1-260C-UNLIM	Ext-Mfg	DSE 6	1.5x1.5x0.75	4.8

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000002	0.0053	53	0.000041	0
Precious Metals	Gold	7440-57-5	0.037735	99.9947	999947	0.780725	7807
Sub-Total			0.037737	100	1000000	0.780767	7808
Die Attach Adhesive							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.019303	30.000155	300002	0.399373	3994
Other Inorganic Materials	Silica	7631-86-9	0.002895	4.499324	44993	0.059897	599
Other Organic Materials	Chlorine	7782-50-5	0.000023	0.035746	357	0.000476	5
Thermoplastics	Epoxy	85954-11-6	0.042122	65.464775	654648	0.871491	8715
Sub-Total			0.064343	100	1000000	1.331237	13312
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	1.732537	97.050022	970500	35.845655	358457
Copper and Its Alloys	Iron	7439-89-6	0.046415	2.599989	26000	0.960312	9603
Copper and Its Alloys	Phosphorus	7723-14-0	0.002678	0.150011	1500	0.055407	554
Zinc and Its Alloys	Zinc	7440-66-6	0.00357	0.199978	2000	0.073862	739
Sub-Total			1.7852	100	1000000	36.935236	369352
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.061104	97.300912	973009	1.264223	12642
Precious Metals	Gold	7440-57-5	0.000188	0.299368	2994	0.00389	39
Precious Metals	Palladium	7440-05-3	0.001319	2.100352	21004	0.02729	273
Precious Metals	Silver	7440-22-4	0.000188	0.299368	2994	0.00389	39
Sub-Total			0.062799	100	1000000	1.299292	12993
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	2.102543	84.39999	844000	43.500965	435010
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	0.130039	5.220008	52200	2.690467	26905
Other Plastics and Rubber	Carbon Black	1333-86-4	0.004484	0.179996	1800	0.092773	928
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.002242	0.089998	900	0.046386	464
Thermoplastics	Epoxy	85954-11-6	0.251857	10.110009	101100	5.210843	52108
Sub-Total			2.491165	100	1000000	51.541434	515414
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.392081	100	1000000	8.112035	81120
Sub-Total			0.392081	100	1000000	8.112035	81120
Total			4.833325			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.